Integrated Device Technology, Inc.
6024 Silver Creek Valley Road
San Jose, CA 96138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A0802-01R1** DATE **May 30, 2008**

Product Affected: 9.0mm x 9.0mm VFQFP-N-64
10.0mm x 10.0mm VFQFP-N-72
6.1mm x 14.0mm TSSOP-56
6.1mm x 17.0mm TSSOP-64

Date Effective: **July 4, 2008**

MEANS OF DISTINGUISHING CHANGED DEVICES:

☐ Product Mark
☒ Back Mark Lot # will have a "Y" suffix
☐ Date Code
☐ Other

Contact: Bimla Paul
Title: Product Quality Assurance
Phone #: (408) 574-6419
Fax #: (408) 284-8362
E-mail: Bimla.Paul@idt.com

Attachment: ☒ Yes ☐ No

Samples: Contact your local IDT sales representative for sample requests.

DESCRIPTION AND PURPOSE OF CHANGE:

☐ Die Technology
☐ Wafer Fabrication Process
☐ Assembly Process
☐ Equipment
☒ Material
☐ Testing
☐ Manufacturing Site
☐ Data Sheet
☐ Other

Revision 1: This notification is a follow-up letter advising our customers that IDT has completed the qualifications on Copper bond wire process for the above mentioned products at Unisem, Indonesia and will start to ship product with copper bond wire process in July 2008.

Attachment 1 - outlines the qualification plans and results.
Attachment 2 - a copy of the original PCN# A0802-01, issued on April 4, 2008.

RELIABILITY/QUALIFICATION SUMMARY:

There is no expected change to the product quality or reliability performance.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ______________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ______________________

E-Mail Address: ______________________

Title: ______________________

Phone# /Fax# : ______________________

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ______________________

DATE: ______________________

ATTACHMENT 1 - PCN # : A0802-01R1

PCN Type: Assembly Material Change - Gold wire to Copper wire

Data Sheet Change: None

Detail Of Change:

Revision 1: This notification is a follow-up letter advising our customers that IDT has completed the qualifications on Copper bond wire process for the above mentioned products at Unisem, Indonesia and will start to ship product with copper bond wire process in July 2008. Please refer to the following for qualification plans and results.

Customers may expect to receive shipments no sooner than 90 days from the issued date of the original PCN# A0802-01, April 4, 2008.

Qualification Test Plan and Test Results:

The following tests were successfully completed.

		VFQFP-N	TSSOP
Test Description	**Test Method**	**Test Results (SS / Rej)**	**Test Results (SS / Rej)**
* High Accelerated Stress Test (Biased, 130 °C/85% RH, 100 Hrs)	JESD22-A110-B	45/0	45/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 1000 Cyc)	JESD22-A104-B	[1]44/0	45/0
High Temp. Storage (150 °C, 1000 Hrs)	JESD22-A103-B	77/0	[2]76/0
Ball Shear Test	JESD22-B116	5/0	5/0
Bond Pull Test	IDT Spec, MAC-3010	5/0	5/0
X-ray Examination	IDT Spec, MAC-3012	45/0	45/0

Note:
* Test requires moisture pre-conditioning sequence per JESD22-A113C and will use the existing moisture sensitivity level that has been qualified for this material set at Unisem, Indonesia.

[1] 1 unit - Functional die level failure, not related to Cu Bond process.

[2] 1 unit - Broken lead hence unable to test at ATE.